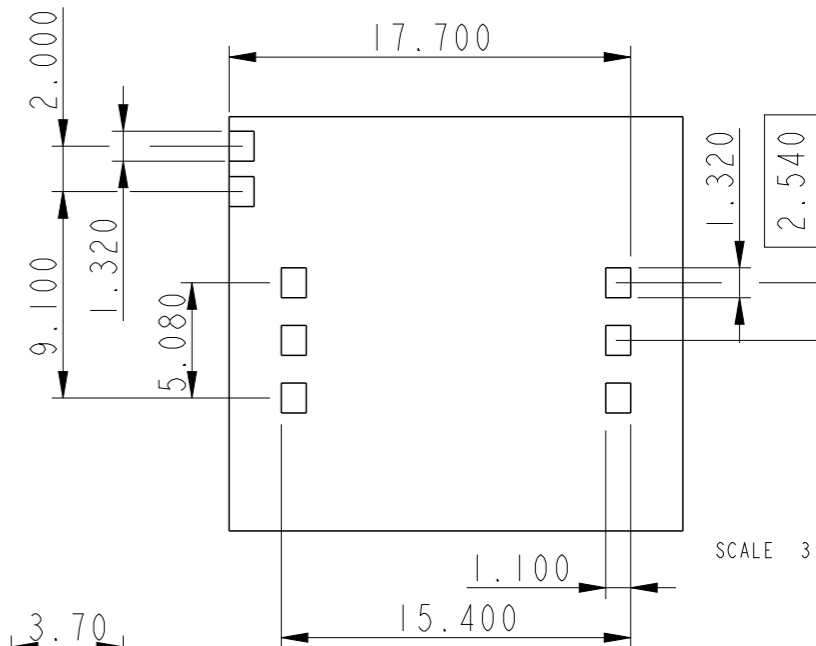
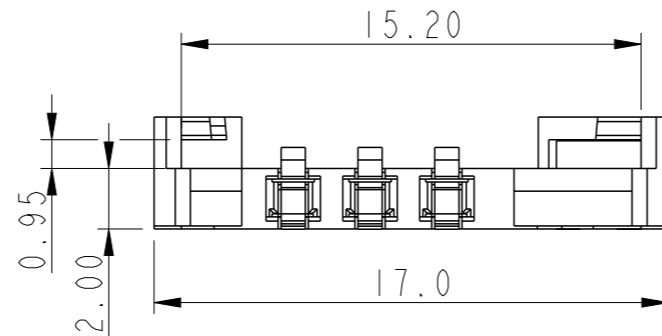
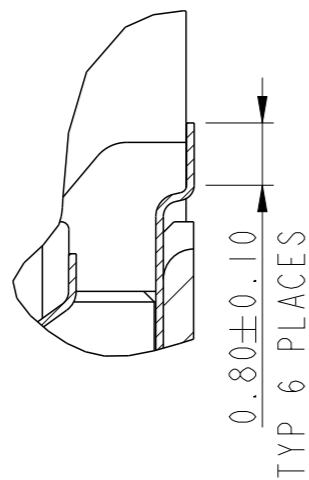


PART NUMBER

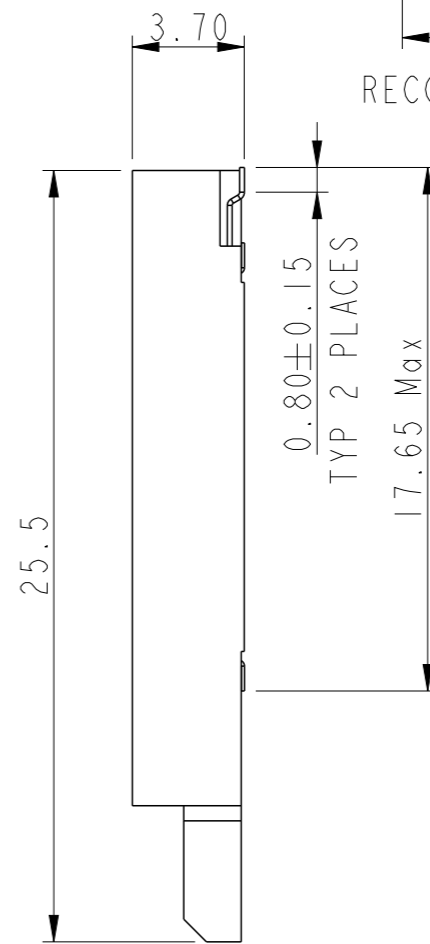
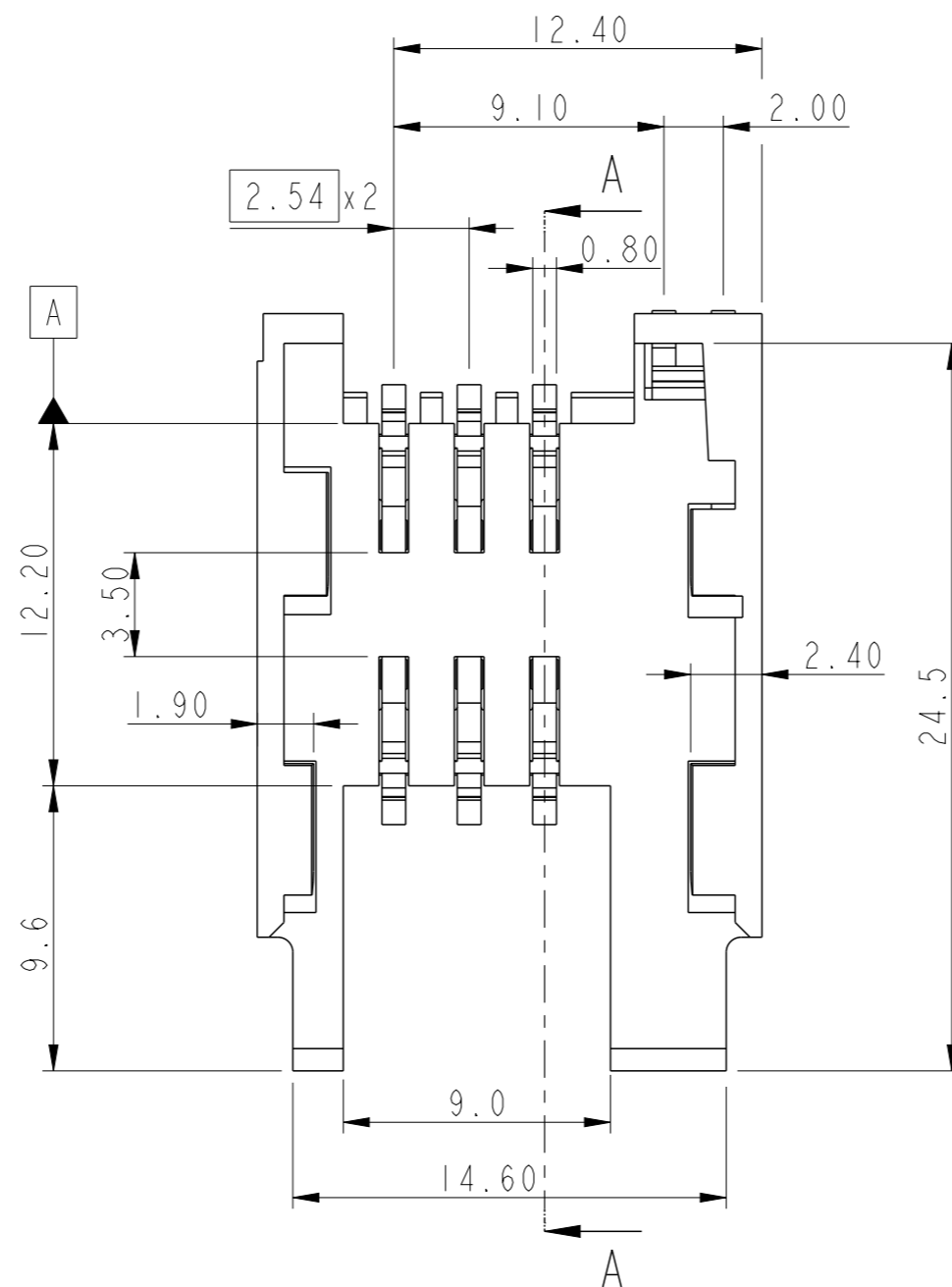
7111SI615A01LF

DETAIL A  
SCALE 10:1

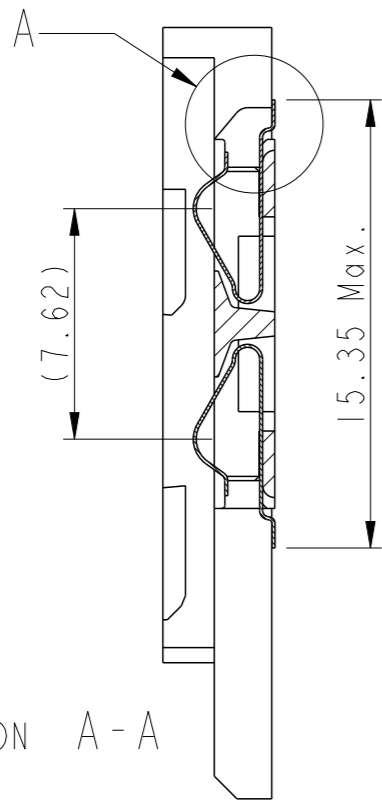


SCALE 3:1

RECOMMENDED PCB LAYOUT



SEE DETAIL A



SECTION A-A

NOTE:

"This product meets European Union Directives and other country regulations as described in GS-47-0004"

The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection reflow oven.

**PROCESSING**

Ni 2 micrometer  
Gold 2.5 µm/Equivalent PdNi over Ni on contact area  
Output : Matte tin 2.5 µm

spec ref	--	dr	P-Mathew Nebu	2011/05/10	projection	mm	size	A3	scale	4:1
tolerance std	ISO 406 ISO 1101	eng	P-Mathew Nebu	2017/09/07			ecn no	ELX-I-27477-1		
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-			rel level	Released		
surface	linear	appr	K-Paul Biju	2017/09/09	product family	MOBILE IO	SIM CARD CONNECTOR WITH SWITCH		dwg no	VJW53943
	angular							TYPE SI6	rev	G
ISO 1302	0.X ±0.5 0.XX ±0.25 0.XXX ±0.1 0° ±2°	cat. no.	SEE NOTES		Product - Customer Drw		sheet 1 of 1			